Materials Declaration

Package	TQFP
Body Size	14 X 14
LeadCount	100
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	1.88 E-02	37018
SiO2 Filler	86	2.02 E-01	397941
Phenol Resin	5	1.18 E-02	23136
Antimony_Sb2O3	0.4	9.41 E-04	1851
Brominated Resin	0.4	9.41 E-04	1851
Carbon Black	0.2	4.70 E-04	925

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	2.04 E-01	401498
Ni	3	6.37 E-03	12521
Si	0.65	1.38 E-03	2713
Mg	0.15	3.18 E-04	626

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.88 E-03	5665

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	5.16 E-03	10142

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.33 E-03	2616

Chip

	% of Chip	Weight (g)	PPM
Si	100	4.00 E-02	78680

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	3.02 E-03	5932
Ag Filler	74	8.58 E-03	16885

Package Totals

Weight (g)	PPM
5.08 E-01	1000000

STS-SU-B

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

Materials Declaration

Package	TQFP
Body Size	14 X 14
LeadCount	100
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	1.88 E-02	37018
SiO2 Filler	86	2.02 E-01	397941
Phenol Resin	5	1.18 E-02	23136
Antimony_Sb2O3	0.4	9.41 E-04	1851
Brominated Resin	0.4	9.41 E-04	1851
Carbon Black	0.2	4.70 E-04	925

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	2.04 E-01	401498
Ni	3	6.37 E-03	12521
Si	0.65	1.38 E-03	2713
Mg	0.15	3.18 E-04	626

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.88 E-03	5665

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	4.38 E-03	8621
Pb	15	7.73 E-04	1521

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.33 E-03	2616

Chip

	% of Chip	Weight (g)	PPM
Si	100	4.00 E-02	78680

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	3.02 E-03	5932
Ag Filler	74	8.58 E-03	16885

Package Totals

Weight (g)	PPM
5.08 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-SU-A

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ADI Proprietary

9/9/04